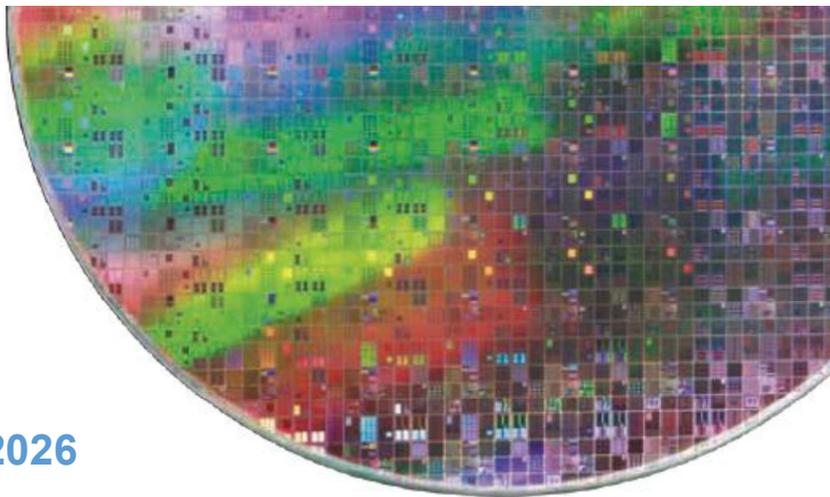


11th CIES Technology Forum



March 23 (Mon) – 24 (Tue), 2026

Muromachi Mitsui Hall & Conference

Progress Report

March 23 (Mon) | **DAY1**

Program

13:30-13:35	Welcome address President, Tohoku Univ.	Teiji Tominaga (Tohoku Univ.)
	Address President, SEMI Japan	Masahiko (Jim) Hamajima (SEMI Japan)
	Address Director-General, Research and Development Bureau, MEXT	Shuichi Sakamoto(MEXT)
13:35-13:55	Address Deputy Director-General, Innovation and Environment Policy Bureau, METI	Wataru Imamura(METI)
	Address Director-General, Patent Examination Department (Electronic Technology), JPO	Masahiro Nishina(JPO)
13:55-14:30	CIES Overview	Tetsuo Endoh (Tohoku Univ.)
14:30-15:00	Industry-academic collaboration STT-MRAM Aimed at Developing Non-Volatile Working Memory and its Manufacturing Technologies	Shoji Ikeda (Tohoku Univ.)
15:30-15:20	Industry-academic collaboration Brain-type processing circuit technologies	Tetsuo Endoh (Tohoku Univ.)
15:20-15:40	Industry-academic collaboration Supersensitive Magnetic Sensors using Ferromagnetic Tunnel Junctions	Mikihiko Oogane (Tohoku Univ.)
15:40-15:55	Break	
15:55-16:10	MEXT X-nics Innovative Spintronics X Semiconductor Research Hub	Tetsuo Endoh (Tohoku Univ.)
16:10-16:25	NEDO AIC Design efficiency of AI processing semiconductors by CMOS/spintronics-hybrid technology and its applications	Takahiro Hanyu (Tohoku Univ.)
16:25-16:45	Industry-academic collaboration Enabling the full potential of SiC bi-directional switches in upcoming power conversion applications	Alberto Castellazzi (Tohoku Univ.)
16:45-17:00	MEXT INNOPEL (Innovative Power Electronics Technologies) Integrated Power Electronics for the Realization of a Decarbonized Society	Yoshikazu Takahashi (Tohoku Univ.)
17:00-17:05	Closing Remarks	Tetsuo Endoh (Tohoku Univ.)

17:30-19:30 Banquet (Participation Fee Required) Venue: Foyer

Organizer:

Center for Innovative Integrated Electronic Systems (CIES), Tohoku University

Co-sponsored:

Research Institute of Electrical Communication (RIEC), Tohoku University

Tohoku University Semiconductor Creativity Hub (S-Hub)

Sponsors:

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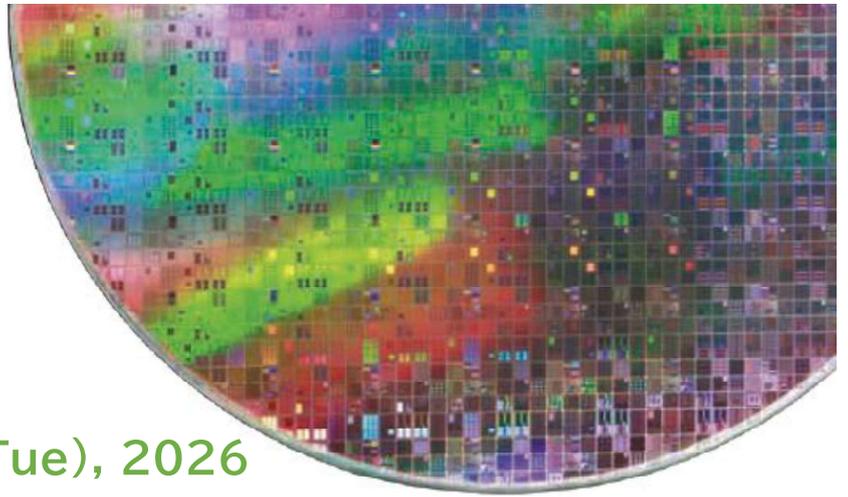
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International Symposium

March
24 (Tue) | **DAY2**

Program

9:00-9:10	Opening remarks	Tetsuo Endoh (Tohoku Univ.)
9:10-9:35	Invited talk 1 An MRAM-based Hybrid Memory Architecture: Possibilities and Challenges	Hiroaki Kobayashi (Tohoku Univ.)
9:35-10:00	Invited talk 2 Demonstration of Embedded MRAM with sub-50 nm MTJ for RAM-like and MCU Applications	Eric Wang (TSMC)
10:00-10:25	Invited talk 3 A 64Gb DDR4 STT-MRAM Using a Timing-Controlled Discharge-Reading Scheme for a 0.001681 μ m ² 1Selector-1MTJ Cross-Point Cell	Kosuke Hatsuda (KIOXIA)
10:25-10:50	Invited talk 4 STT-MRAM for Last Level Cache	Daniel Worledge (IBM)
10:50-11:15	Invited talk 5 AI Datacenters leveraging IOWN technologies	Yuichi Ikejiri (NTT)
11:15-11:35	Invited talk 6 Next Generation Solid-State-Transformer Concepts for AI Datacenters	Johann W. Kolar (ETH Zurich)
11:35-12:00	Invited talk 7 Exploring Reinforcement Learning Algorithms for Power Electronics	Uwe Drofenik (TU Wien)
12:00-12:25	Invited talk 8 Technological Trends in Power Modules and Power Devices for automotive applications	Takuya Kadoguchi (DENSO)
12:25-12:30	Closing remarks	Tetsuo Endoh (Tohoku Univ.)

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